

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A structure comprising a substrate bearing, on at least part of its surface, a photocatalytic antisoiling layer ~~based on~~ comprising titanium dioxide (TiO_2), ~~characterized in that~~ wherein said photocatalytic antisoiling layer is coated with a thin nonporous layer, ~~containing~~ comprising silicon and oxygen and having a covering power, wherein said thin nonporous layer capable of mechanically and chemically ~~protecting~~ protects the underlying photocatalytic layer, while maintaining the photocatalytic activity of the titanium dioxide (TiO_2) TiO_2 .

Claim 2 (Currently Amended): The structure ~~as claimed in~~ of claim 1, ~~characterized in that~~ wherein said thin nonporous layer ~~containing~~ comprising silicon and oxygen is present in the form of a continuous film.

Claim 3 (Currently Amended): The structure ~~of claim 1 as claimed in either of~~ claims 1 and 2, characterized in that wherein said thin layer ~~containing~~ comprising silicon and oxygen is present in the form of a film that conforms to the surface asperities of the underlying photocatalytic antisoiling layer.

Claim 4 (Currently Amended): The structure ~~of claim 1 as claimed in one of claims 1 to 3, characterized in that~~ wherein the thin nonporous layer ~~containing~~ comprising silicon and oxygen is a layer of at least one silicon-oxygen compound ~~chosen from~~ selected from the group consisting of SiO_2 , $SiOC$, $SiON$, SiO_x , where wherein $x < 2$, and $SiOCH$.

Claim 5 (Currently Amended): The structure of claim 1 as claimed in one of claims 1 to 4, characterized in that wherein the thin nonporous layer containing comprising silicon and oxygen is a layer of at least one silicon-oxygen compound with which further comprising at least one compound chosen selected from the group consisting of Al₂O₃ and ZrO₂ is associated.

Claim 6 (Currently Amended): The structure as claimed in claim 5, characterized in that wherein the Al/Si, the Zr/Si, or the Al/Si and Zr/Si (Al and/or Zr)/Si atomic ratio does not exceed 1.

Claim 7 (Currently Amended): The structure of claim 5 as claimed in either of claims 5 and 6, characterized in that wherein the structure comprises Al₂O₃ and wherein the Al/Si ratio is between from 0.03 and to 0.5, in particular between 0.05 and 0.1.

Claim 8 (Currently Amended): The structure of claim 5 as claimed in one of claims 5 to 7, characterized in that wherein the structure comprises ZrO₂ and wherein the Zr/Si ratio is between from 0.05 and to 0.4.

Claim 9 (Currently Amended): The structure of claim 1 as claimed in one of claims 1 to 8, characterized in that wherein the thin nonporous layer containing comprising silicon and oxygen has a thickness of at most 15 nm, especially at most 10 nm and in particular at most 8 nm, being preferably at most 5 nm, or about 5 nm, in particular 2 to 3 nm.

Claim 10 (Currently Amended): The structure as claimed in ~~claim 1 one of claims 1 to 9, characterized in that wherein the photocatalytic antisoiling layer titanium dioxide-based layer~~ consists of TiO₂ alone or of TiO₂ doped with at least one dopant chosen especially selected from[[;]] the group consisting of N[[;]] pentavalent cations such as of Nb, pentavalent cations of Ta and pentavalent cations of V, [[;]] Fe, [[;]] and Zr.

Claim 11 (Currently Amended): The structure ~~of claim 1 as claimed in one of claims 1 to 10, characterized in that wherein the TiO₂-based layer photocatalytic antisoiling layer has been deposited by~~

a sol-gel method,

or by a pyrolysis, especially chemical vapor deposition, method

or by room-temperature vacuum sputtering,

~~where appropriate magnetron and/or ion beam sputtering, using a metal or TiO_x target, where wherein x<2, and in an oxidizing atmosphere, or using a TiO₂ target in an inert atmosphere, the TiO₂ produced by the sputtering then having possibly optionally being subjected to a heat treatment so as to be in the crystallized state in a photocatalytically active form.~~

Claim 12 (Currently Amended): The structure ~~as claimed in of claim 1 one of claims 1 to 11, characterized in that wherein the thin nonporous layer containing comprising silicon and oxygen has been deposited by room-temperature vacuum sputtering, where appropriate magnetron and/or ion beam sputtering, using a target of Al (8 at%)-doped Si, in an Ar/O₂ atmosphere, at a pressure of 0.2 Pa.~~

Claim 13 (Currently Amended): The structure of claim 1 as claimed in one of claims 1 to 12, characterized in that it includes further comprising, immediately below the photocatalytic antisoiling layer TiO₂-based layer, an underlayer having a crystallographic structure for assisting in the crystallization, by heteroepitaxial growth, in the anatase form of the TiO₂-based photocatalytic antisoiling upper layer, especially an underlayer consisting of A_xTiO₃ where A denotes barium or strontium.

Claim 14 (Currently Amended): The structure of claim 1 as claimed in one of claims 1 to 13, characterized in that wherein the substrate consists of comprises a sheet, whether plane or having curved faces, wherein the sheet comprises at least one material selected from the group consisting of monolithic glass, or laminated glass, glass-ceramic, [[or]] and a hard thermoplastic, such as polycarbonate, or else of glass fibers, or glass-ceramic fibers, wherein said sheets sheet or said fibers having, where appropriate, have, optionally, received at least one other functional layer before application of the TiO₂-based layer photocatalytic antisoiling layer or of or have, optionally, received a layer for assisting in the crystallization of the latter photocatalytic antisoiling layer by heteroepitaxial growth.

Claim 15 (Currently Amended): The structure as claimed in of claim 14, comprising the at least one other functional layer, wherein characterized in that the at least one other functional layer or the other functional layers are chosen is selected from the group consisting of layers at least one layer having an optical functionality, at least one thermal control layer layers and at least one conducting layer layers, and wherein also, if the substrate is made of

comprises glass or glass-ceramic, the at least one other functional layer acts layers acting as a barrier to the migration of alkali metals from the glass or from the glass-ceramic.

Claim 16 (Currently Amended): A process for manufacturing [[a]] the structure of claim 1 as defined in one of claims 1 to 15, comprising characterized in that depositing an optionally doped TiO₂ layer is deposited on a substrate made of comprising glass, or glass-ceramic, or polycarbonate-type hard plastic, of the sheet type, or on glass fibers, or glass-ceramic fibers,

wherein said optionally doped TiO₂ layer being is optionally subjected to a heat treatment in order to give it a photocatalytic property if this the photocatalytic property is not provided by the conditions used for depositing the optionally doped TiO₂ layer, it, and

depositing then a thin layer containing comprising silicon and oxygen as defined in one of claims 1 to 9 is deposited on said photocatalytic layer, to form the structure of claim 1.

Claim 17 (Currently Amended): The process as claimed in of claim 16, characterized in that wherein the deposition of [[a]] the TiO₂ layer and that of the thin layer containing comprising silicon and oxygen are carried out in succession at room temperature, by vacuum sputtering, where appropriate magnetron and/or ion beam sputtering, in the same chamber, the conditions being the following:

- for depositing the TiO₂-based layer, supply in AC or DC mode, at a pressure of 1-3 mbar and in an oxygen/inert gas (argon) atmosphere, using a Ti or TiO_x, target, where x = 1.5 to 2; and

for depositing the layer ~~containing comprising~~ silicon and oxygen, supply in AC mode at a pressure of 0.1 to 1.0 Pa and in an Ar/O₂ atmosphere using a target having a high silicon content,

the deposition of the TiO₂ layer being optionally preceded by the deposition of an underlayer for assisting in the crystallization by epitaxial growth in the anatase form of the TiO₂ layer.

Claim 18 (Currently Amended): The process of claim 16 as claimed in either of claims 16 and 17, in which the coating of wherein the substrate is a glass or glass-ceramic substrate is carried out, wherein characterized in that, before application of the TiO₂ layer or of the underlayer associated therewith, at least one layer forming a barrier to the migration of alkali metals present in the glass or glass-ceramic substrate is deposited on the substrate, and wherein, optionally, an annealing or toughening operation then possibly being is carried out [,.] after the TiO₂ layer and the thin silicon-based layer covering the latter TiO₂ layer have been deposited, at a temperature of between 250°C and 550°C, preferably between 350°C and 500°C, in the case of the annealing operation and at a temperature of at least 600°C in the case of the toughening operation.

Claim 19 (Currently Amended): The process of claim 18 as claimed in one of claims 16 to 18, characterized in that wherein, after the optional application of the at least one layer forming a barrier to the migration of alkali metals and before application of the TiO₂ layer or the underlayer associated with the latter, at least one functional layer selected from the group consisting of at least one layer chosen from layers having an optical functionality, at least one thermal control layers layer, and at least one conducting layer layers is deposited, wherein

said ~~functional layers at least one functional layer is being~~ advantageously deposited by vacuum sputtering, ~~where appropriate magnetron and/or ion-beam sputtering.~~

Claim 20 (Currently Amended): ~~A single Single or multiple glazing, in particular for motor vehicles or buildings, comprising, on at least one face respectively, [[a]] the structure as defined in claim 1 one of claims 1 to 15, said face being especially that facing the outside, or possibly also that facing the inside.~~

Claim 21 (New): The structure of claim 11, wherein the TiO₂ is subjected to a heat treatment so as to be in the crystallized state in a photocatalytically active form.

Claim 22 (New): The structure of claim 11, wherein the room-temperature vacuum sputtering comprises magnetron sputtering.

Claim 23 (New): The structure of claim 11, wherein the room-temperature vacuum sputtering comprises ion-beam sputtering.

Claim 24 (New): The structure of claim 11, wherein the room-temperature vacuum sputtering comprises magnetron sputtering and ion-beam sputtering.

Claim 25 (New): The structure of claim 14, wherein the sheet or the fibers have received at least one other functional layer before application of the photocatalytic antisoiling layer.

Claim 26 (New): The structure of claim 14, comprising a layer for assisting in the crystallization of the photocatalytic antisoiling layer by heteroepitaxial growth.

Claim 27 (New): The process of claim 16, wherein the TiO₂ layer is doped.

Claim 28 (New): The process of claim 17, comprising depositing an underlayer for assisting in the crystallization by epitaxial growth in the anatase form of the TiO₂ layer.

Claim 29 (New): The process of claim 18, comprising carrying out an annealing operation, wherein the annealing operation is carried out at a temperature of between 250°C and 500°C.

Claim 30 (New): The process of claim 18, comprising carrying out a toughening operation, wherein the toughening operation is carried out at a temperature of at least 600°C.